

Product/Process Change Notification

N° 2021-113-A4

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting products TLE926x

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-08-23.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board Dr. Wolfgang Eder

Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2021-113-A4_[customer-no].pdf

Detailed change information

Subject: Several changes affecting products TLE926x

Reason/Motivation: Infineon is extending manufacturing capabilities and will enable product families at external manufacturing partners.
 Infineon has continuously extended its production capacity to meet strongly increasing market demand. This extension includes not only building up of new fabs or new lines but also optimization of production location and usage of outsourcing if necessary.
 Infineon is ensuring business continuity and high supply security by optimizing and streamlining its production.

Description	Old	New
DATA SHEET: Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	Rev. 1.1	Rev. 1.2 (see links in 4_cip21113_A4)
DESIGN: Design changes in active elements	S9263C (Dresden)	S9263C (Dresden) AND S9263U (UMC)
DESIGN: Design changes in routing	S9263C (Dresden)	S9263C (Dresden) AND S9263U (UMC)
PROCESS - WAFER PRODUCTION: New wafer diameter	200mm (Dresden)	200mm (Dresden) AND 300mm (UMC)
PROCESS - WAFER PRODUCTION: New final wafer thickness	220 µm (Dresden)	220 µm (Dresden) AND 230 µm (UMC)
PROCESS - WAFER PRODUCTION: New / change of metallization / vias / contacts	NiMoP	NiMoP AND Pro.Cu

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PROCESS - WAFER PRODUCTION: Change in process technology not covered by any other type of change	Old process flow	Old process flow AND New process flows
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site	Locations: Dresden Split Flow: Infineon Technologies Dresden GmbH, Dresden, Germany Infineon Technologies AG, Regensburg, Germany	Locations: Dresden Split Flow (200mm): Infineon Technologies Dresden GmbH, Dresden, Germany Infineon Technologies AG, Regensburg, Germany AND UMC Split Flow 1 (300mm): United Microelectronics Corporation, Tainan, Taiwan Infineon Technologies Dresden GmbH, Dresden, Germany AND UMC Split Flow 2 (300mm): United Microelectronics Corporation, Tainan, Taiwan Infineon Technologies Dresden GmbH, Dresden, Germany Infineon Technologies AG, Regensburg, Germany
PROCESS - ASSEMBLY: Change in leadframe dimensions	PG-VQFN-48-31 (Melaka)	PG-VQFN-48-31/37 (Melaka) AND PG-VQFN-48-79 (Amkor)
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	PG-VQFN-48-31 (Melaka)	PG-VQFN-48-31/37 (Melaka) AND PG-VQFN-48-79 (Amkor)
PROCESS - ASSEMBLY: Die attach material	CRM1079S (Melaka)	CRM1079S (Melaka) AND CRM1085A (Amkor)
PROCESS - ASSEMBLY: Change of wire bonding	PG-VQFN-48-31: Cu (Melaka)	PG-VQFN-48-31/37: Cu (Melaka) PG-VQFN-48-79: PCC (palladium coated copper) (Amkor)
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	EME G700 (Melaka)	EME G700 (Melaka) AND EME G631 (Amkor)

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PROCESS - ASSEMBLY: Change of product marking	Without serial number above the date code in line 3 (Melaka)	Without serial number above the date code in line 3 (Melaka) AND With serial number above the date code in line 3 (Amkor)
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site	Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia	Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia AND Amkor Technology, INC. Muntinlupa City, Philippines
EQUIPMENT: Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	Infineon tool park	Infineon tool park AND SiFo and OSAT tool park

Product identification

Wafer lot numbers from Dresden start with ZAxxxxxx.
Wafer lot numbers from UMC start with 6Hxxxxxx.
Traceability assured via date code.
No change in SP ordering number

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.

DeQuMa-ID(s): SEM-DS-01 / SEM-DE-01 / SEM-DE-02 / SEM-PW-02 / SEM-PW-03 / SEM-PW-07 / SEM-PW-09 / SEM-PW-13 / SEM-PA-03 / SEM-PA-04 / SEM-PA-07 / SEM-PA-08 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-EQ-01

Attachments

PCN_2021-113-A4_[customer-no].pdf	affected product list
4_cip21113_A4	MyICP links

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2023-01-30
Last order date (LOD) [2]	2023-01-30
Last delivery date (LDD) [3]	2024-01-30

[1] Provided date or earlier after customer approval.

[2] Last date where orders for unchanged products will be accepted.

[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

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MyICP links

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Data sheets download

› MyICP links to the Infineon data base

Sales Code	Data sheet folder	Revision
TLE9261-3BQX	MyICP (Link)	Rev. 1.2
TLE9261-3BQX V33	MyICP (Link)	
TLE9261BQX	MyICP (Link)	
TLE9261BQX V33	MyICP (Link)	
TLE9262-3BQX	MyICP (Link)	
TLE9262-3BQX V33	MyICP (Link)	
TLE9262BQX	MyICP (Link)	
TLE9262BQX V33	MyICP (Link)	
TLE9263-3BQX	MyICP (Link)	
TLE9263-3BQX V33	MyICP (Link)	
TLE9263BQX	MyICP (Link)	
TLE9263BQX V33	MyICP (Link)	

TLE926x UMC EMC test reports



› MyICP links to the Infineon data base

FE site	BE site	IBEE Zwickau	SAE J2962-1/2
UMC	Amkor	Pass (CAN/LIN , CAN-FD)	Pass (Link)
UMC	Infineon in-house	Pass (CAN/LIN , CAN-FD)	Pass (refer to Amkor package)



Part of your life. Part of tomorrow.

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Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
TLE9263BQX	SP001611048	TLE9263BQXXUMA1	PG-VQFN-48-31	TLE9263BQXXUMA1